Product/process change notification

PCN N° 2022-028-A

Dear customer,

Please find attached our Infineon Technologies AG PCN:

Capacity extension for dedicated Gen10.7 products by introduction of additional wafer manufacturing site at Samsung Electronics Co. Ltd., Korea and Infineon Technologies Dresden, Germany

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **2022-03-18**
- Infineon aligns with the widely recognized JEDEC STANDARD **“JESD46“,** which stipulates: **“Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”**

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

On 16 April 2020, Infineon acquired Cypress.
We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.
For further details, please visit our website:
https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/

Infineon Technologies AG
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Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Constanze Hufenbecher, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

Product/process change notification

PCN N° 2022-028-A

Products affected	Please refer to attached affected product list 1_cip22028_a

Detailed change information

Subject	Capacity extension for dedicated Gen10.7 products by introduction of additional wafer manufacturing site at Samsung Electronics Co. Ltd., Korea and Infineon Technologies Dresden, Germany	
Reason	Extension of wafer manufacturing sites for additional capacity to ensure continuity of supply and flexible manufacturing	
Description	**Old**	**New**
Wafer Production Location	▪ Newport Wafer Fab Ltd. (NWF Ltd.), United Kingdom ▪ Vanguard International Semiconductor Corporation, Taiwan ▪ Tower Semiconductor Ltd., Israel ▪ Infineon Technologies Dresden GmbH, Dresden, Germany	▪ Existing Wafer Production Locations see “old” ▪ Samsung Electronics Co, Ltd., Korea ▪ Infineon Technologies Dresden GmbH, Germany

Product identification	Internal and external traceability is assured via SP number, country of diffusion, and wafer lot number (refer to 3_cip22028_a)
Impact of change	**NO** change on electrical, thermal parameters and reliability as proven via product qualification and characterization **NO** change in existing datasheet parameters **NO** change in quality and reliability. Processes are optimized to meet product performance according to already applied Infineon specification

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- **Attachments**

1_cip22028_a	affected product list
2_cip22028_a	qualification report
3_cip22028_a	customer information package

- **Time schedule**

Final qualification report	available
First samples available	on request
Intended start of delivery	2022-04-01 (or earlier based on customer approval)

If you have any questions, please do not hesitate to contact your local sales office.

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Qualification Test Report

PCN N^{o} 2022-028-A **Date: 2021-11-08**

Capacity extension for dedicated Gen10.7 products by introduction of additional wafer manufacturing site at Samsung Electronics Co. Ltd., Korea and Infineon Technologies Dresden, Germany

Reason for choosing the following test vehicles:

IRFP4668PBF - TO-247	Thru-Hole
IRFB4110PBF - TO-220	Thru-Hole
IRFB4310ZPBF - TO-220	Thru-Hole
IRFS4010TRL7PP - D2PAK 7L	Surface Mount
IRFS4229TRLPBF - D2PAK 3L	Surface Mount
IRFR4620TRLPBF - DPAK	Surface Mount

Scope of qualification: Gen 10.7 Technology Transfer to Samsung

Assessment of Q-Results: Pass
*Note: MSL & Preconditioning not done on Thru-Hole Devices

Stress test	Abbreviation	Test conditions	Readout	IRFP4668PBF	IRFB4110PBF	IRFB4310ZPBF	IRFS4010TRL7PP	IRFS4229TRLPBF	IRFR4620TRLPBF
				fails / stressed	fails / stressed	fails / stressed	fails / stressed	fails / stressed	fails / stressed
MSL Preconditioning JESD22-A113	**PC**	MSL 1	0h	N/A on Thru-Hole	N/A on Thru-Hole	N/A on Thru-Hole	0 / 330	0 / 330	0 / 330
Temperature Cycling JESD22-A104	**TC**	with preconditioning -55°C to 150°C	1000 x	0 / 77	0 / 77	0 / 77	0 / 77	0 / 77	0 / 77
Unbiased Temperature/Humidity JESD22-A118	**UHAST**	with preconditioning Ta = 130°C, RH = 85%	96 h	0 / 77	0 / 77	0 / 77	0 / 77	0 / 77	0 / 77
High Humidity High Temp. Reverse Bias JESD22-A101	**H3TRB**	with preconditioning T = 85 °C; RH = 85% Vds = 80% max up to 100 V	1000 h	0 / 77	0 / 77	0 / 77	0 / 77	0 / 77	0 / 77
High Temperature Reverse Bias JESD22-A108	**HTRB**	Tj = Tj max VCE = 80% Vds max	1000 h	0 / 77	0 / 77	0 / 77	0 / 77	0 / 77	0 / 77
High Temperature Gate stress JESD22-A108	**HTGS**	Ta = Max °C VGS = ±80% Vgs	1000 h	0 / 77	0 / 77	0 / 77	0 / 77	0 / 77	0 / 77
Intermitted Operational Life Test MIL-STD 750/Meth.1037	**IOL**	with preconditioning 'Delta T = 100 K n = 8572 cyc	1000 h	--	0 / 77	0 / 77	0 / 77	0 / 77	--
Intermitted Operational Life Test MIL-STD 750/Meth.1037	**IOL**	with preconditioning 'Delta T = 100 K n = 6000 cyc	1000 h	0 / 77	--	--	--	--	--
Intermitted Operational Life Test MIL-STD 750/Meth.1037	**IOL**	with preconditioning 'Delta T = 100 K n = 15000 cyc	1000 h	--	--	--	--	--	0 / 77

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Qualification Test Report

PCN N^{O} 2022-028-A **Date: 2021-11-08**

Capacity extension for dedicated Gen10.7 products by introduction of additional wafer manufacturing site at Samsung Electronics Co. Ltd., Korea and Infineon Technologies Dresden, Germany

Reason for choosing the following test vehicles:

IRFB4110PBF	Large Die, TO-220*	Thru-Hole
IRFS4010PBF	Large Die, 3L D2PAK/TO-263	Surface-Mount
IRFS4010-7PPBF	Large Die, 7L D2PAK/TO-263	Surface-Mount
IRFR3607PBF	Med Die, DPAK/TO-252	Surface-Mount
IRFB4310ZPBF	Med Die, TO-220*	Thru-Hole
IRFS4310ZPBF	Med Die, DPAK/TO-252	Surface-Mount
IRLB4030PBF	Large Die, TO-220*	Thru-Hole
IRFP4332PBF	Large Die, TO-247*	Thru-Hole
IRFS4229PBF	Large Die, D2PAK/TO-263	Surface-Mount
IRFP4868PBF	Large Die, TO-247*	Thru-Hole

Scope of qualification: Gen 10.7 Technology Transfer to Dresden Fab

Assessment of Q-Results: Pass
*Note: MSL and Preconditioning not done on Thru-Hole Devices

Stress test	Abbreviation	Test conditions	Readout	IRFB4110PBF	IRFS4010PBF	IRFS4010-7PPBF	IRFR3607PBF	IRFB4310ZPBF	IRFB4310ZPBF	IRFS4310ZPBF	IRLB4030PBF	IRFP4332PBF	IRFS4229PBF	IRFP4868PBF
				fails / stressed	fails / stressed	fails / stressed	fails / stressed	fails / stressed	fails / stressed	fails / stressed	fails / stressed	fails / stressed	fails / stressed	fails / stressed
MSL Preconditioning JESD22-A113	**PC**	MSL 1	0h	N/A*	0 / 1155	0 / 924	0 / 924	N/A*	N/A*	0 / 308	N/A*	N/A*	0 / 462	N/A*
Temperature Humidity Bias JESD22-A101	**THB**	with preconditioning T = 85°C; RH = 85% Vds = 80% V	1000 h	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 77	0 / 77	0 / 77	Referenced by IRFB4110PBF	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 77
Temperature Humidity Bias JESD22-A101	**THB**	with preconditioning T = 85°C; RH = 85% Vds = 100% V	1000 h	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	--	--	--	--	--	--	--	--	--
Temperature Cycling JESD22-A104	**TC**	with preconditioning -55°C to 150°C	1000 x	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 77	0 / 77	0 / 77	Referenced by IRFB4110PBF	Referenced by IRFB4110PBF	Referenced by IRFS4010PBF	Referenced by IRFB4110PBF
Unbiased Temperature/Humidity JESD22-A118	**UHAST**	with preconditioning Ta = 130°C, RH = 85%	96 h	--	--	--	0 / 231 (3 lots x 77)	--	0 / 77	0 / 77	--	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 77
Autoclave JESD22-A102	**AC**	with preconditioning Ta = 121°C RH = 100%	96 h	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	--	0 / 77	--	--	Referenced by IRFB4110PBF	Referenced by IRFB4110PBF	--	--
High Temperature Reverse Bias JESD22-A108	**HTRB**	Tj = Tj max VCE = 80% VCE max	1000 h	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 77	0 / 77	0 / 77	Referenced by IRFB4110PBF	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 77
High Temperature Reverse Bias JESD22-A108	**HTRB**	Tj = Tj max VCE = 100% VCE max	1000 h	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	--	--	--	--	--	--	--	--
High Temperature Gate Stress/Bias JESD22-A108	**HTGS/HTGB**	Ta = Max °C Vgs = 80% V	1000 h	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 77	0 / 77	0 / 77	--	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 77
High Temperature Gate Stress/Bias JESD22-A108	**HTGS/HTGB**	Ta = Max °C Vgs = 100% V	1000 h	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	--	--	--	--	0 / 231 (3 lots x 77)	--	--	--
Intermitted Operational Life Test MIL-STD 750/Meth.1037	**IOL**	with preconditioning Delta T = 100 K Ton = 3.5 min Toff = 3.5 min n = 8572 cyc	1000 h	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	0 / 231 (3 lots x 77)	--	0 / 77	0 / 77	0 / 77	Referenced by IRFB4110PBF	Referenced by IRFB4110PBF	Referenced by IRFS4010PBF	Referenced by IRFB4110PBF
Intermitted Operational Life Test MIL-STD 750/Meth.1037	**IOL**	with preconditioning Delta T = 100 K Ton = 2 min Toff = 2 min n = 15000 cyc	1000 h	--	--	--	0 / 231 (3 lots x 77)	--	--	--	--	--	--	--

Sales Name	Package	Change Description		
		Additional Wafer Production Location		Additional SP Number*
		Samsung Electronics Co, Ltd., Korea	Infineon Technologies Dresden GmbH, Germany	
64-0090PBF	PG-TO220-3	x		x
64-2123PBF	PG-TO263-3	x		
64-2138PBF	PG-TO263-3	x		
64-2152PBF	PG-TO263-3	x		
64-2162PBF	PG-TO263-3	x	x	
IRF100B202	PG-TO220-3	x	x	x
IRF1018EPBF	PG-TO220-3	x	x	x
IRF1018ESTRLPBF	PG-TO263-3	x		
IRF200B211	PG-TO220-3	x		
IRFB3004PBF	PG-TO220-3	x		x
IRFB3006GPBF	PG-TO220-3	x		x
IRFB3006PBF	PG-TO220-3	x		x
IRFB3077PBF	PG-TO220-3	x		x
IRFB3206GPBF	PG-TO220-3	x		x
IRFB3206PBF	PG-TO220-3	x		x
IRFB3207ZGPBF	PG-TO220-3	x		x
IRFB3207ZPBF	PG-TO220-3	x		x
IRFB3256PBF	PG-TO220-3	x		x
IRFB3306GPBF	PG-TO220-3	x		x
IRFB3306PBF	PG-TO220-3	x		x
IRFB3307ZPBF	PG-TO220-3	x		x
IRFB3407ZPBF	PG-TO220-3	x		x
IRFB3607PBF	PG-TO220-3	x		x
IRFB3806PBF	PG-TO220-3	x		x
IRFB4019PBF	PG-TO220-3	x	x	x
IRFB4020PBF	PG-TO220-3	x	x	
IRFB4110GPBF	PG-TO220-3	x		x
IRFB4110PBF	PG-TO220-3	x		x
IRFB4115PBF	PG-TO220-3	x		x
IRFB4127PBF	PG-TO220-3	x		x
IRFB4227PBF	PG-TO220-3	x		x
IRFB4228PBF	PG-TO220-3	x		x
IRFB4229PBF	PG-TO220-3	x		
IRFB4310ZPBF	PG-TO220-3	x		x
IRFB4321PBF	PG-TO220-3	x		x
IRFB4332PBF	PG-TO220-3	x		
IRFB4410ZGPBF	PG-TO220-3	x		x
IRFB4410ZPBF	PG-TO220-3	x		x
IRFB4510PBF	PG-TO220-3	x		x
IRFB4615PBF	PG-TO220-3	x		x
IRFB4620PBF	PG-TO220-3	x		
IRFB5615PBF	PG-TO220-3	x		x
IRFB5620PBF	PG-TO220-3	x		
IRFI3306GPBF	PG-TO220-3	x		
IRFI4019H-117P	PG-TO220-3	x		
IRFI4020H-117P	PG-TO220-3	x		
IRFI4110GPBF	PG-TO220-3	x		
IRFI4227PBF	PG-TO220-3	x		
IRFI4229PBF	PG-TO220-3	x		
IRFI4321PBF	PG-TO220-3	x		
IRFI4410ZPBF	PG-TO220-3	x		
IRFP3006PBF	PG-TO247-3	x		x
IRFP3077PBF	PG-TO247-3	x		x
IRFP3206PBF	PG-TO247-3	x		x
IRFP3306PBF	PG-TO247-3	x		x
IRFP4110PBF	PG-TO247-3	x		x
IRFP4127PBF	PG-TO247-3	x		x
IRFP4227PBF	PG-TO247-3	x		x
IRFP4229PBF	PG-TO247-3	x		x
IRFP4310ZPBF	PG-TO247-3	x		x
IRFP4321PBF	PG-TO247-3	x		x
IRFP4332PBF	PG-TO247-3	x		x
IRFP4368PBF	PG-TO247-3	x		x
IRFP4468PBF	PG-TO247-3	x		x
IRFP4568PBF	PG-TO247-3	x		x
IRFP4668PBF	PG-TO247-3	x		x
IRFP4768PBF	PG-TO247-3	x		x
IRFR1018ETRPBF	PG-TO252-3	x	x	
IRFR3607TRPBF	PG-TO252-3	x	x	
IRFR3806TRPBF	PG-TO252-3	x	x	
IRFR4510TRPBF	PG-TO252-3	x		
IRFR4615TRLPBF	PG-TO252-3	x		
IRFR4620TRLPBF	PG-TO252-3	x		
IRFS3004TRL7PP	PG-TO263-7	x		

IRFS3004TRLPBF	PG-TO263-3	x		
IRFS3006TRL7PP	PG-TO263-7	x		
IRFS3006TRLPBF	PG-TO263-3	x		
IRFS3107TRL7PP	PG-TO263-7	x		
IRFS3107TRLPBF	PG-TO263-3	x		
IRFS3206TRRPBF	PG-TO263-3	x		
IRFS3207ZTRRPBF	PG-TO263-3	x		
IRFS3306TRLPBF	PG-TO263-3	x		
IRFS3307ZTRLPBF	PG-TO263-3	x		
IRFS3307ZTRRPBF	PG-TO263-3	x		
IRFS3607TRLPBF	PG-TO263-3	x	x	
IRFS3806TRLPBF	PG-TO263-3	x		
IRFS4010TRL7PP	PG-TO263-7	x		
IRFS4010TRLPBF	PG-TO263-3	x		
IRFS4020TRLPBF	PG-TO263-3	x		
IRFS4115TRL7PP	PG-TO263-7	x		
IRFS4115TRLPBF	PG-TO263-3	x		
IRFS4127TRLPBF	PG-TO263-3	x		
IRFS4227TRLPBF	PG-TO263-3	x		
IRFS4229TRLPBF	PG-TO263-3	x		
IRFS4310ZTRLPBF	PG-TO263-3	x		
IRFS4321TRL7PP	PG-TO263-7	x		
IRFS4321TRLPBF	PG-TO263-3	x		
IRFS4321TRRPBF	PG-TO263-3	x		
IRFS4410ZTRLPBF	PG-TO263-3	x		
IRFS4510TRLPBF	PG-TO263-3	x		
IRFS4615TRLPBF	PG-TO263-3	x		
IRFS4620TRLPBF	PG-TO263-3	x		
64-2128PBF-CU-V	PG-TO263-3	x	x	
64-2145PBF	PG-TO263-3		x	
64-2147PBF	PG-TO263-3		x	
IRLS4030TRL7PP	PG-TO263-7		x	
64-2140PBF	PG-TO263-3	x		
64-2141PBF-V	PG-TO263-3	x		

**** Only for Assembly and Test Location at Great Team Backend Foundry, Inc., China***

PCN N° 2022-028-A

Capacity extension for dedicated Gen10.7 products by introduction of additional wafer manufacturing site at Samsung Electronics Co. Ltd., Korea and Infineon Technologies Dresden, Germany

Sales name	SP number	OPN	Package
64-0090PBF	SP001574300	64-0090PBF	PG-TO220-3
64-2123PBF	SP001560764	64-2123PBF	PG-TO263-3
64-2128PBF-CU-V	SP001693762	64-2128PBF-CU-V	PG-TO263-3
64-2138PBF	SP001574276	64-2138PBF	PG-TO263-3
64-2140PBF	SP001569346	64-2140PBF	PG-TO263-3
64-2141PBF-V	SP001693778	64-2141PBF-V	PG-TO263-3
64-2145PBF	SP001553638	64-2145PBF	PG-TO263-3
64-2147PBF	SP001569338	64-2147PBF	PG-TO263-3
64-2152PBF	SP001575010	64-2152PBF	PG-TO263-3
64-2162PBF	SP001575018	64-2162PBF	PG-TO263-3
IRF100B202	SP001561488	IRF100B202	PG-TO220-3
IRF1018EPBF	SP001574502	IRF1018EPBF	PG-TO220-3
IRF1018ESTRLPBF	SP001564496	IRF1018ESTRLPBF	PG-TO263-3
IRF200B211	SP001561622	IRF200B211	PG-TO220-3
IRFB3004PBF	SP001572420	IRFB3004PBF	PG-TO220-3
IRFB3006GPBF	SP001577692	IRFB3006GPBF	PG-TO220-3
IRFB3006PBF	SP001570606	IRFB3006PBF	PG-TO220-3
IRFB3077PBF	SP001575594	IRFB3077PBF	PG-TO220-3
IRFB3206GPBF	SP001565784	IRFB3206GPBF	PG-TO220-3
IRFB3206PBF	SP001566480	IRFB3206PBF	PG-TO220-3
IRFB3207ZGPBF	SP001554560	IRFB3207ZGPBF	PG-TO220-3
IRFB3207ZPBF	SP001575584	IRFB3207ZPBF	PG-TO220-3
IRFB3256PBF	SP001577830	IRFB3256PBF	PG-TO220-3
IRFB3306GPBF	SP001555952	IRFB3306GPBF	PG-TO220-3
IRFB3306PBF	SP001556002	IRFB3306PBF	PG-TO220-3
IRFB3307ZPBF	SP001564038	IRFB3307ZPBF	PG-TO220-3
IRFB3407ZPBF	SP001560202	IRFB3407ZPBF	PG-TO220-3
IRFB3607PBF	SP001551746	IRFB3607PBF	PG-TO220-3
IRFB3806PBF	SP001572380	IRFB3806PBF	PG-TO220-3
IRFB4019PBF	SP001572370	IRFB4019PBF	PG-TO220-3
IRFB4020PBF	SP001564028	IRFB4020PBF	PG-TO220-3
IRFB4110GPBF	SP001556050	IRFB4110GPBF	PG-TO220-3
IRFB4110PBF	SP001570598	IRFB4110PBF	PG-TO220-3
IRFB4110PBF	SP005732686	IRFB4110PBFXKMA1	PG-TO220-3
IRFB4115PBF	SP001565902	IRFB4115PBF	PG-TO220-3
IRFB4127PBF	SP001560212	IRFB4127PBF	PG-TO220-3
IRFB4227PBF	SP001565892	IRFB4227PBF	PG-TO220-3
IRFB4227PBF	SP005582179	IRFB4227PBFAKSA1	PG-TO220-3
IRFB4228PBF	SP001575554	IRFB4228PBF	PG-TO220-3

Sales name	SP number	OPN	Package
IRFB4229PBF	SP001565910	IRFB4229PBF	PG-TO220-3
IRFB4310ZPBF	SP001570588	IRFB4310ZPBF	PG-TO220-3
IRFB4321PBF	SP001577790	IRFB4321PBF	PG-TO220-3
IRFB4332PBF	SP001556040	IRFB4332PBF	PG-TO220-3
IRFB4410ZGPBF	SP001554600	IRFB4410ZGPBF	PG-TO220-3
IRFB4410ZPBF	SP001564008	IRFB4410ZPBF	PG-TO220-3
IRFB4510PBF	SP001566724	IRFB4510PBF	PG-TO220-3
IRFB4615PBF	SP001565882	IRFB4615PBF	PG-TO220-3
IRFB4620PBF	SP001563998	IRFB4620PBF	PG-TO220-3
IRFB5615PBF	SP001575534	IRFB5615PBF	PG-TO220-3
IRFB5620PBF	SP001565852	IRFB5620PBF	PG-TO220-3
IRFI3306GPBF	SP001556626	IRFI3306GPBF	PG-TO220-3
IRFI4019H-117P	SP001560458	IRFI4019H-117P	PG-TO220-3
IRFI4019H-117P	SP005547284	IRFI4019H-117PXKMA1	PG-TO220-5
IRFI4020H-117P	SP001556636	IRFI4020H-117P	PG-TO220-3
IRFI4020H-117P	SP005547286	IRFI4020H-117PXKMA1	PG-TO220-5
IRFI4110GPBF	SP001556598	IRFI4110GPBF	PG-TO220-3
IRFI4227PBF	SP001564096	IRFI4227PBF	PG-TO220-3
IRFI4229PBF	SP001575824	IRFI4229PBF	PG-TO220-3
IRFI4321PBF	SP001556676	IRFI4321PBF	PG-TO220-3
IRFI4410ZPBF	SP001566742	IRFI4410ZPBF	PG-TO220-3
IRFP3006PBF	SP001556714	IRFP3006PBF	PG-TO247-3
IRFP3077PBF	SP001566982	IRFP3077PBF	PG-TO247-3
IRFP3206PBF	SP001578056	IRFP3206PBF	PG-TO247-3
IRFP3306PBF	SP001564200	IRFP3306PBF	PG-TO247-3
IRFP4110PBF	SP001556724	IRFP4110PBF	PG-TO247-3
IRFP4127PBF	SP001566148	IRFP4127PBF	PG-TO247-3
IRFP4127PBF	SP005596353	IRFP4127PBFAKMA1	PG-TO247-3
IRFP4227PBF	SP001560510	IRFP4227PBF	PG-TO247-3
IRFP4229PBF	SP001578046	IRFP4229PBF	PG-TO247-3
IRFP4310ZPBF	SP001572864	IRFP4310ZPBF	PG-TO247-3
IRFP4321PBF	SP001575756	IRFP4321PBF	PG-TO247-3
IRFP4332PBF	SP001578038	IRFP4332PBF	PG-TO247-3
IRFP4332PBF	SP005582181	IRFP4332PBFXKMA1	PG-TO247-3
IRFP4368PBF	SP001556774	IRFP4368PBF	PG-TO247-3
IRFP4468PBF	SP001554960	IRFP4468PBF	PG-TO247-3
IRFP4568PBF	SP001560548	IRFP4568PBF	PG-TO247-3
IRFP4668PBF	SP001572854	IRFP4668PBF	PG-TO247-3
IRFP4768PBF	SP001571028	IRFP4768PBF	PG-TO247-3

PCN N° 2022-028-A

Capacity extension for dedicated Gen10.7 products by introduction of additional wafer manufacturing site at Samsung Electronics Co. Ltd., Korea and Infineon Technologies Dresden, Germany

Sales name	SP number	OPN	Package
IRFR1018ETRPBF	SP001566962	IRFR1018ETRPBF	PG-TO252-3
IRFR3607TRPBF	SP001567010	IRFR3607TRPBF	PG-TO252-3
IRFR3806TRPBF	SP001564890	IRFR3806TRPBF	PG-TO252-3
IRFR4510TRPBF	SP001567870	IRFR4510TRPBF	PG-TO252-3
IRFR4615TRLPBF	SP001560646	IRFR4615TRLPBF	PG-TO252-3
IRFR4620TRLPBF	SP001552208	IRFR4620TRLPBF	PG-TO252-3
IRFS3004TRL7PP	SP001557236	IRFS3004TRL7PP	PG-TO263-7
IRFS3004TRLPBF	SP001557246	IRFS3004TRLPBF	PG-TO263-3
IRFS3006TRL7PP	SP001552266	IRFS3006TRL7PP	PG-TO263-7
IRFS3006TRLPBF	SP001567578	IRFS3006TRLPBF	PG-TO263-3
IRFS3107TRL7PP	SP001571528	IRFS3107TRL7PP	PG-TO263-7
IRFS3107TRLPBF	SP001576238	IRFS3107TRLPBF	PG-TO263-3
IRFS3206TRRPBF	SP001573508	IRFS3206TRRPBF	PG-TO263-3
IRFS3207ZTRRPBF	SP001565050	IRFS3207ZTRRPBF	PG-TO263-3
IRFS3306TRLPBF	SP001568056	IRFS3306TRLPBF	PG-TO263-3
IRFS3307ZTRLPBF	SP001565042	IRFS3307ZTRLPBF	PG-TO263-3
IRFS3307ZTRRPBF	SP001568048	IRFS3307ZTRRPBF	PG-TO263-3
IRFS3607TRLPBF	SP001578296	IRFS3607TRLPBF	PG-TO263-3
IRFS3806TRLPBF	SP001573492	IRFS3806TRLPBF	PG-TO263-3
IRFS4010TRL7PP	SP001557352	IRFS4010TRL7PP	PG-TO263-7
IRFS4010TRLPBF	SP001550124	IRFS4010TRLPBF	PG-TO263-3
IRFS4020TRLPBF	SP001573468	IRFS4020TRLPBF	PG-TO263-3
IRFS4115TRL7PP	SP001550134	IRFS4115TRL7PP	PG-TO263-7
IRFS4115TRLPBF	SP001578272	IRFS4115TRLPBF	PG-TO263-3
IRFS4127TRLPBF	SP001557360	IRFS4127TRLPBF	PG-TO263-3
IRFS4227TRLPBF	SP001567810	IRFS4227TRLPBF	PG-TO263-3
IRFS4229TRLPBF	SP001557392	IRFS4229TRLPBF	PG-TO263-3
IRFS4310ZTRLPBF	SP001557376	IRFS4310ZTRLPBF	PG-TO263-3
IRFS4321TRL7PP	SP001568024	IRFS4321TRL7PP	PG-TO263-7
IRFS4321TRLPBF	SP001565002	IRFS4321TRLPBF	PG-TO263-3
IRFS4321TRRPBF	SP001565026	IRFS4321TRRPBF	PG-TO263-3
IRFS4410ZTRLPBF	SP001567800	IRFS4410ZTRLPBF	PG-TO263-3
IRFS4510TRLPBF	SP001557402	IRFS4510TRLPBF	PG-TO263-3
IRFS4615TRLPBF	SP001573450	IRFS4615TRLPBF	PG-TO263-3
IRFS4620TRLPBF	SP001568008	IRFS4620TRLPBF	PG-TO263-3
IRLS4030TRL7PP	SP001569054	IRLS4030TRL7PP	PG-TO263-7

PCN N° 2022-028-A

Capacity extension for dedicated Gen10.7 products by introduction of additional wafer manufacturing site at Samsung Electronics Co. Ltd., Korea and Infineon Technologies Dresden, Germany

Sales name	SP number	OPN	Package